

AMENDMENTS TO THE CLAIMS

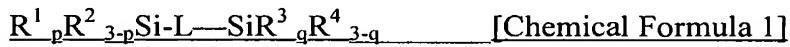
This listing of claims will replace all prior versions, and listings, of claims in the application.

Listings of Claims:

1. (Currently Amended) A method for preparing an organosilicate polymer comprising the steps of:

i) mixing a thermally decomposable organic silane compound ~~that is capped with silane compounds at both its ends represented by the following Chemical Formula 1~~, and a silane compound or a silane oligomer ~~selected from the group consisting of compounds represented by the following Chemical Formula 2, Chemical Formula 3, and Chemical Formula 4~~; and

ii) [[then]] adding water and a catalyst thereto ~~to conduct, and conducting~~ hydrolysis and condensation;



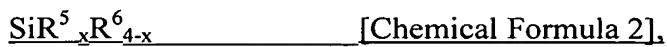
wherein

R¹ and R³ are independently a hydrogen, fluorine, aryl, vinyl, allyl, or linear or branched C1-4 alkyl unsubstituted or substituted with fluorine;

R² and R⁴ are independently an acetoxy, hydroxyl, or linear or branched C1-4 alkoxy;

L is polyalkyleneoxide; and

p and q are respectively an integer of 0 to 2;



wherein

R⁵ is independently a hydrogen, fluorine, aryl, vinyl, allyl, or linear or branched C1-4 alkyl unsubstituted or substituted with fluorine;

R⁶ is independently an acetoxy, hydroxyl, or linear or branched C1-4 alkoxy; and

x is an integer of 0 to 2,



wherein

R⁷ and R⁹ are independently a hydrogen, fluorine, aryl, vinyl, allyl, or linear or branched C1-4 alkyl unsubstituted or substituted with fluorine;

R⁸ and R¹⁰ are independently an acetoxy, hydroxyl, or linear or branched C1-4 alkoxy;

M is C1-6 alkylene or phenylene; and
y and z are respectively an integer of 0 to 2,

[Chemical Formula 4]



wherein

R¹¹ are independently a hydrogen, fluorine, aryl, vinyl, allyl, or linear or branched C1-4 alkyl unsubstituted or substituted with fluorine;

R¹² is independently a hydroxy, or a linear or branched C1-4 alkoxy; and m and n are respectively an integer of 3 to 10.

2. (Currently Amended) The method for preparing an organosilicate polymer according to claim 1, wherein the thermally decomposable organic silane compound that is capped with silane compounds at both its ends are represented by the following Chemical Formula 1:

[Chemical Formula 1]



wherein

R¹ and R³ are independently a hydrogen, fluorine, aryl, vinyl, allyl, or linear or branched C1-4 alkyl unsubstituted or substituted with fluorine;

R² and R⁴ are independently an acetoxy, hydroxyl, or linear or branched C1-4 alkoxy;

L is polyalkyleneoxide; and

p and q are respectively an integer of 0 to 2 is selected from the consisting of bis-methyldimethoxysilylpropyl polypropyleneoxide, a bis-trimethoxysilylpropyl(polyethyleneoxide-b-polypropyleneoxide-b-polyethyleneoxide), and a mixture thereof.

3. (Currently Amended) The method for preparing an organosilicate polymer according to claim [[2]] 1, wherein the organic substance that can be thermally decomposed at 450° C or less is selected from a group consisting of ether, ester, anhydride, carbonate, carbamate, acrylate, epoxy, isocyanate, and amide compounds the weight average molecular weight of the polyalkyleneoxide is from 300 to 100,000.

4. (Canceled)

5. (Canceled)

6. (Currently Amended) An organosilicate polymer prepared by ~~mixing a thermally decomposable organic silane compound that is capped with silane compounds at both its ends, and a silane compound or silane oligomer, and then adding water and a catalyst to conduct hydrolysis and condensation~~ the method according to claim 1, wherein the ~~thermally decomposable organic silane compound represented by the Chemical Formula 1, and the silane compound or the silane oligomer selected from the group consisting of compounds represented by the Chemical Formula 2, Chemical Formula 3, and Chemical Formula 4 are connected with a covalent bond.~~

7. (Currently Amended) A coating composition for forming an insulating film, which comprises:

- a) an organosilicate polymer ~~according to claim 6 comprising~~
 - i) ~~a thermally decomposable organic silane compound that is capped with silane compounds at both its ends, and~~
 - ii) ~~a silane compound or silane oligomer; and~~
- b) an organic solvent.

8. (Withdrawn) A method for manufacturing a low dielectric insulating film for a semiconductor device, which comprises the steps of: a) providing a solution of a coating composition for forming an insulating film comprising: i) an organosilicate polymer comprising a thermally decomposable organic silane compound that is capped with silane compounds at both its ends, and a silane compound or silane oligomer, and ii) an organic solvent ; b) coating the a) solution on a substrate of a semiconductor device to form an insulating film ; and c) drying and firing the b) coated insulating film.

9. (Withdrawn) An insulating film for a semiconductor device prepared by the method of claim 8.

10. (Withdrawn) A semiconductor device comprising an insulating film for a semiconductor device prepared by the method of claim 8.